

Amendments to the Specification:

Page 1, before line 1, insert:

Cross Reference to Related Application

This application is a 35 USC § 371 National Phase Entry Application from PCT/JP2004/010101, filed July 15, 2004, and designating the United States.

Please replace the first full paragraph on page 18 with the following amended paragraph:

When the first resin composition is obtained, 20 to 80 parts by weight of an epoxy resin (containing a curing agent), 20 to 80 parts by weight of an aromatic polyamide resin polymer soluble in a solvent, and a curing accelerating agent added as required in an adequate quantity are mixed to form a resin mixture. When the second resin composition is obtained, ~~20~~ 5 to 50 parts by weight of an epoxy resin (containing a curing agent), 50 to 95 parts by weight of a polyether sulfone resin, and a curing accelerating agent added as required in an adequate quantity are mixed to form a resin mixture. Since the description for each component and compounding proportion is as described above, and the description here is duplicated, the description thereof will be omitted.

Please replace Example 3 on page 25 and 26 with the following amended Example:
Example 3

In this example, a silane coupling agent layer was formed on the shinny surface of an untreated ~~18-~~μ ~~18~~μ copper foil same as in Example 1 having a surface

roughness Rz of 1.1 μm, and an ultra thin primer resin layer was formed on the surface thereof using the second resin composition to produce a copper foil with an ultra thin adhesive layer. Since the first resin composition in Example 1 was merely substituted by the second resin composition described below, and the description of each step will be repetitive, the description of the repetitive parts will be omitted here, and only the second resin composition and the results of evaluation will be described.